

MA2C188 (MA188)

Silicon epitaxial planar type

For high speed and high voltage switching, small-power rectification

■ Features

- Allowing to insert into a 5 mm pitch hole
- High voltage (V_R : 200 V) rectification is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Maximum peak reverse voltage	V_{RM}	250	V
Power dissipation (Average)	$P_{D(AV)}$	400	mW
Output current	I_O	200	mA
Repetitive peak forward current	I_{FRM}	625	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	175	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 to +175	$^\circ\text{C}$

Note) *: $t = 1\text{ s}$

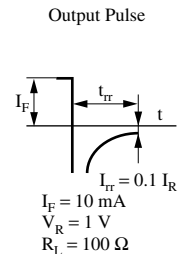
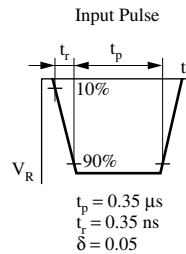
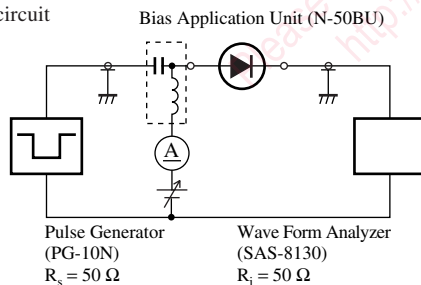
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200\text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100\ \mu\text{A}$	250			V
Reverse current	I_R	$V_R = 200\text{ V}$			200	nA
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		1.0		pF
Reverse recovery time *	t_{rr}	$I_F = 10\text{ mA}, V_R = 1\text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100\ \Omega$			60	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 20 MHz.

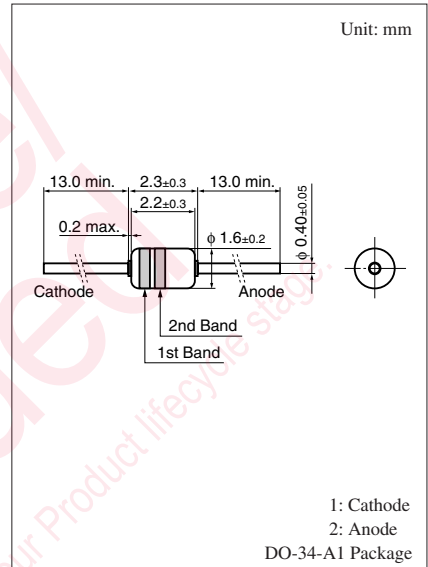
3. *: t_{rr} measurement circuit

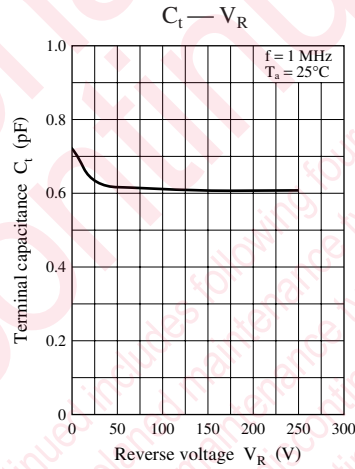
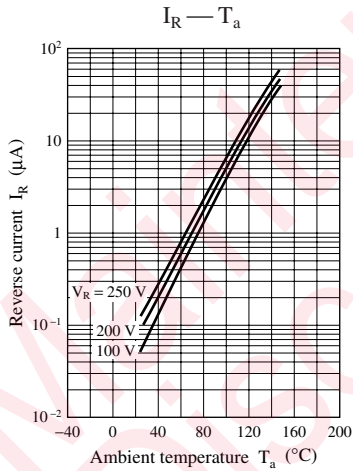
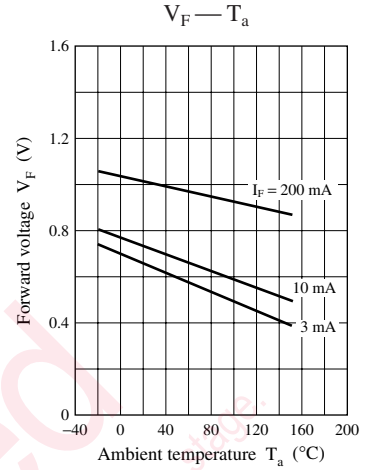
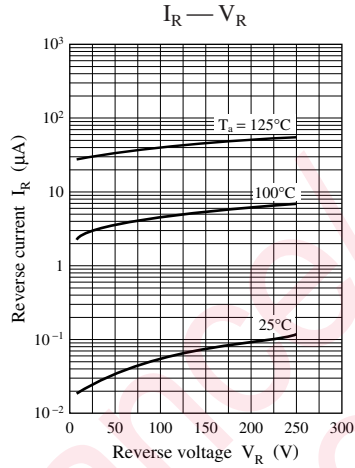
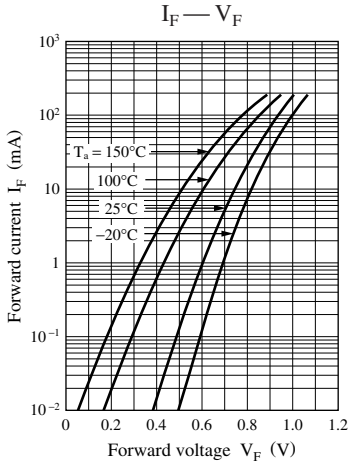


■ Cathode Indication

Type No.		
Color	1st Band	Blue
	2nd Band	Green

Note) The part number in the parenthesis shows conventional part number.





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